

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

TI-26239

**Chee Kiang Yew, et al.**

Serial No: 09/401,572

Filed: 09/22/1999

For: Direct Attachment Semiconductor Chip To Organic Substrate

**DECLARATION AND POWER OF ATTORNEY  
NOT ACCOMPANYING APPLICATION**

As a below named inventor, I declare that my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor if only one name is listed below, or an original, first and joint inventor if plural inventors are named below, of the subject matter which is claimed and for which a patent is sought on the invention entitled as set forth below, which is described and claimed in U. S. Patent Application S.N. 09/401,572, filed 09/22/1999; that I have reviewed and understand the contents of the specification, including the claims, as amended by any amendment specifically referred to in the oath or declaration; that no application for patent or inventor's certificate on this invention has been filed by me or my legal representatives or assigns in any country foreign to the United States of America prior to the filing date of said application; and that I acknowledge my duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

Title of Invention:	<i>Direct Attachment Semiconductor Chip To Organic Substrate</i>
---------------------	--

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Power of Attorney: As a named inventor, I hereby appoint the following attorney(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith, (list name and registration number):

Wade James Brady III, Reg. #32,080  
Jay M. Cantor, Reg. #19,906  
Robby T. Holland, Reg. #33,304  
William B. Kempler, Reg. #28,228

Ronald O. Neerings, Reg. #34,227  
Robert N. Rountree, Reg. #39,347  
Frederick J. Telecky, Jr., Reg. #29,979  
Customer Number 23494

Please send correspondence to:

Michael K. Skrchor  
Patents Department  
Texas Instruments Incorporated  
P.O. Box 655474, MS 3999  
Dallas, TX 75265

and direct telephone calls to:

(972) 917-5653

Name of Inventor:

Chee Kiang Yew

Residence and P.O.

22 Cedarwood Grove  
Singapore 738376

Citizenship:

Singapore

Signature of Inventor:

Date:

9 - April - 2003

Name of Inventor:

Masazumi Amagai

Residence and P.O.

4260 Aza  
Hiji, Oita, Japan

Citizenship:

Japanese

Signature of Inventor:


Date:

# APPLICATION FOR UNITED STATES PATENT

## DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I declare that my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor if only one name is listed below, or an original, first and joint inventor if plural inventors are named below, of the subject matter which is claimed and for which a patent is sought on the invention entitled as set forth below, which is described in the attached specification; that I have reviewed and understand the contents of the specification, including the claims, as amended by any amendment specifically referred to in the oath or declaration; that no application for patent or inventor's certificate on this invention has been filed by me or my legal representatives or assigns in any country foreign to the United States of America; except in Singapore, and that I acknowledge my duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, section 1.56(a);

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

<b>TITLE OF INVENTION:</b> <b>DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE</b>		
<b>POWER OF ATTORNEY:</b> I HEREBY APPOINT THE FOLLOWING ATTORNEYS TO PROSECUTE THIS APPLICATION AND TRANSACT ALL BUSINESS IN THE PATENT AND TRADEMARK OFFICE CONNECTED THEREWITH		
Tammy L. Williams, Reg. No. 38,860 Robby T. Holland, Reg. No. 33,304 Richard L. Donaldson, Reg. No. 25,673	William B. Kempler, Reg. No. 28,228 Jay Cantor, Reg. No. 19,906 Arthur I. Navarro, Reg. No. 40,744	Warren L. Franz, Reg. No. 28,716 Gary C. Honeycutt, Reg. No. 20,250
<b>SEND CORRESPONDENCE TO:</b> Gary C. Honeycutt Texas Instruments Incorporated, P. O. Box 655474, M/S 3999 Dallas, Texas 75265		<b>DIRECT TELEPHONE CALLS TO:</b> Gary C. Honeycutt (972) 238-7160
<b>NAME OF INVENTOR: (1)</b>  Chee Kiang Yew	<b>NAME OF INVENTOR: (2)</b>  Masazumi Amagai	<b>NAME OF INVENTOR: (3)</b>  
<b>RESIDENCE (City and State Only)</b>  	<b>RESIDENCE (City and State Only)</b>  	<b>RESIDENCE (City and State Only)</b>  
<b>POST OFFICE ADDRESS</b> Blk 866, # 04-313 Woodlands, St 83, Singapore 830866	<b>POST OFFICE ADDRESS</b> 4260 Aza Hiji, Oita, Japan	<b>POST OFFICE ADDRESS</b>  
<b>COUNTRY OF CITIZENSHIP:</b>  Singapore	<b>COUNTRY OF CITIZENSHIP:</b>  Japanese	<b>COUNTRY OF CITIZENSHIP:</b>  
<b>SIGNATURE OF INVENTOR:</b>  	<b>SIGNATURE OF INVENTOR:</b>  	<b>SIGNATURE OF INVENTOR:</b>  
<b>DATE:</b>  	<b>DATE:</b> 9/21/99	<b>DATE:</b>  